

SURFACE MOUNT SUPER FAST RECOVERY RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
- ◆ 250°C/10 seconds at terminals
- ◆ Glass passivated chip junction

Mechanical Data

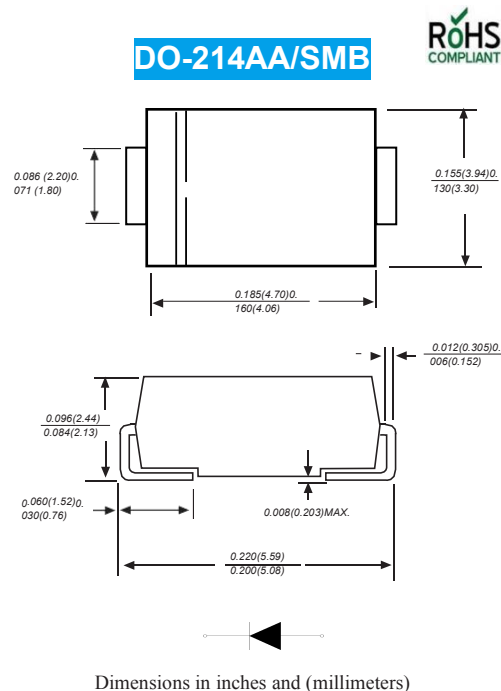
Case : JEDEC DO-214AA/SMB Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.003 ounce, 0.1grams



Maximum Ratings And Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

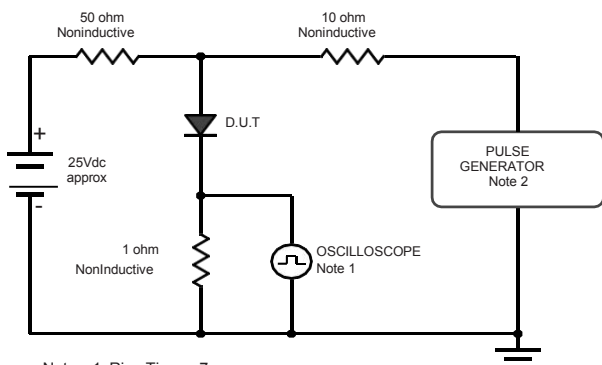
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	RCD ES3AB	RCD ES3BB	RCD ES3CB	RCD ES3DB	RCD ES3EB	RCD ES3GB	RCD ES3JB	UNITS
Marking Code									
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	V_{DC}	50	100	150	200	300	400	600	V
Maximum average forward rectified current at $T_L=100^{\circ}C$	$I_{(AV)}$	3.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	90							A
Maximum instantaneous forward voltage at 3.0A	V_F	1			1.25		1.68		V
Maximum DC reverse current at rated DC blocking voltage	I_R	5							μA
Maximum reverse recovery time (NOTE 1)	t_{rr}	100							ns
Typical junction capacitance (NOTE 2)	C_J	35							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$ $R_{\theta JC}$	45							$^{\circ}C/W$
Operating junction and storage temperature range	T_J, T_{STG}	50 16							$^{\circ}C$
		-55 to +150							

Note: 1.Reverse recovery condition $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$
 2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.3.
 P.C.B. mounted with 2.0"x2.0" (5.0x5.0cm) copper pad areas

Ratings And Characteristic Curves

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
 Input Impedance = 1megohm,22pF.2
 . Rises Time =10ns, max.
 Source Impedance = 50 ohms.

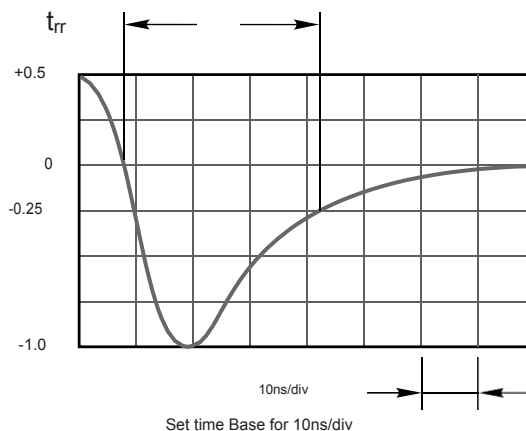


Fig.2 Maximum Average Forward Current Rating

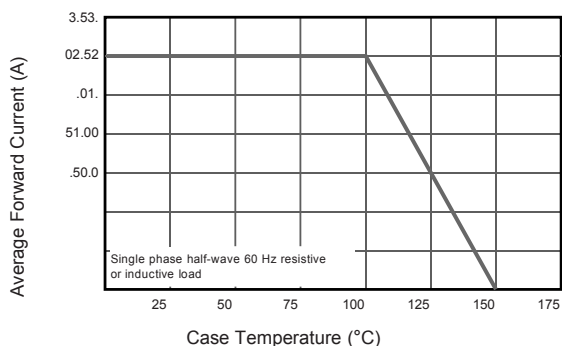


Fig.3 Typical Reverse Characteristics

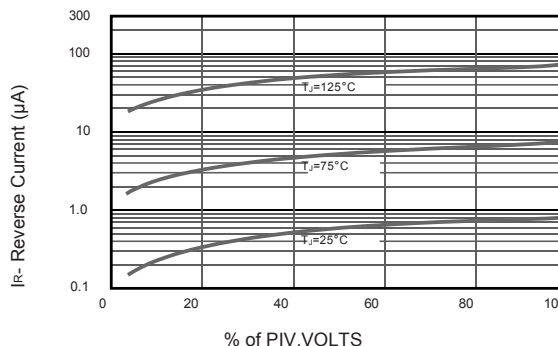


Fig.4 Typical Forward Characteristics

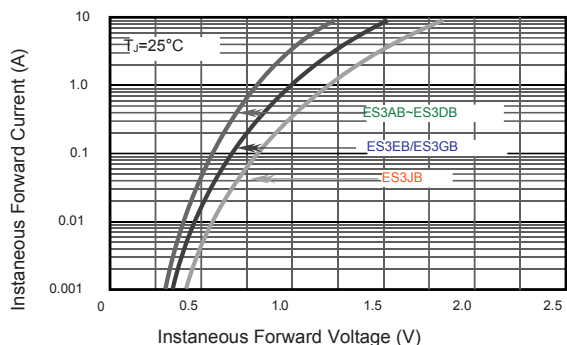


Fig.5 Typical Junction Capacitance

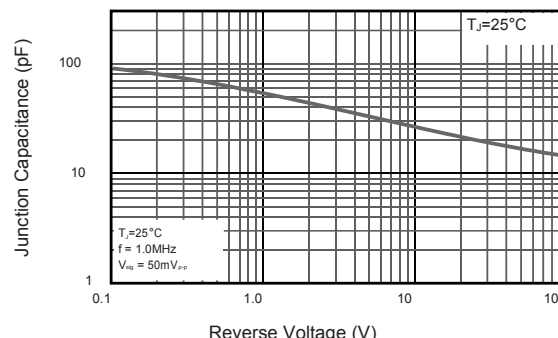
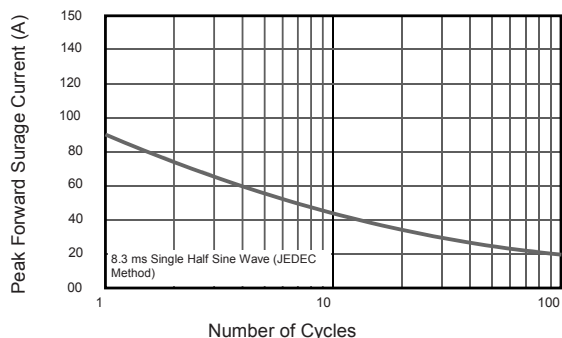
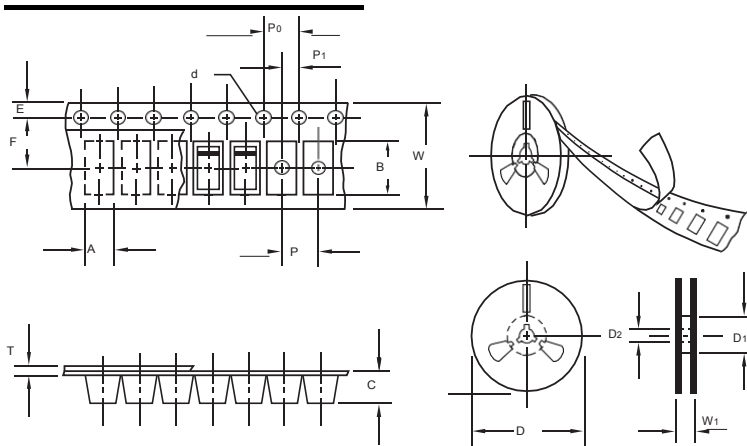


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current





unit:mm

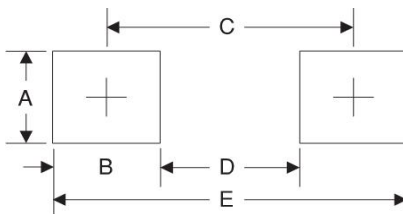
Item	Symbol	Tolerance	SMB
Carrier width	A	0.1	3.81
Carrier length	B	0.1	5.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.55
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	12.00
Reel width	W ₁	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMB	13"	3,000	4.0	6,000	190*190*41	330	365*365*360	48,000	14.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
AB	2.82	0.1100
C	.44	.0940
DE	62.2	1810
	7.0	0860
		276